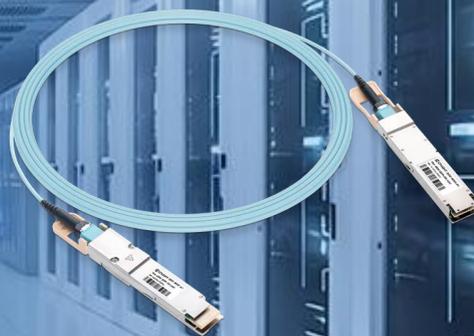


Product Specification

QDD-QDD-A to QDD-QDD-A Active Optical Cable

PN:QDD-QDD-A



Features

- Hot Pluggable QSFP-DD form factor
- Available length range 1~100m
- Active Optical Cable
- Operating data rate 425Gbps
- Single +3.3V power supply
- Max power dissipation $\leq 11W$
- 8-Channel Full-Duplex Active Optical Cable
- Commercial temperature range 0°C to 70°C

Compliance

- Compliant with QSFP-DD MSA
- Compliant with Electrical Interface SFF-8679
- IEEE802.3bj,IEEE802.3cd
- RoHS

Applications

- 400G Ethernet
- High Performance Computing (HPC)
- Data Center & Networking Equipment
- Switches with QSFP-DD ports

Description

The QDD-QDD-A provides a high-performance, low-power solution for high-speed interconnections in data centers and cloud networks. Designed for relatively short connections, this cable enables reliable and efficient 400G data transmission over thin, flexible optical fibers, eliminating the need for additional optical components. Its compact and lightweight design makes it an ideal high-density solution for system providers and customers implementing 400G infrastructure, ensuring seamless connectivity in space-constrained environments.

Compliant with industry standards such as IEEE 802.3cd, OIF-CEI-04.0, QSFP-DD MSA, and QSFP-DD-CMIS-rev4p0, the QDD-QDD-A guarantees interoperability and reliable performance across a wide range of networking equipment. It offers a cost-effective alternative to traditional copper cables, delivering superior signal integrity and lower latency over longer distances compared to passive copper solutions. With its plug-and-play simplicity and robust construction, this AOC is perfect for high-bandwidth applications, including data center interconnects, high-performance computing, and enterprise networks.

The QDD-QDD-A combines energy efficiency, high reliability, and exceptional performance, making it a future-proof choice for modern networking needs. By reducing power consumption and simplifying deployment, it helps organizations optimize their infrastructure while meeting the growing demands of data-intensive applications. Whether for short-reach interconnects or high-density configurations, this AOC ensures a scalable and efficient solution for next-generation networks.

Product performance Specifications

1、 Basic Product Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit
Storage Temperature	T _s	-40		85	°C
Operating Case Temperature	T _c	0		70	°C
Relative Humidity	RH	0		85	%
Power Supply Voltage	V _{cc}	3.135	3.3	3.465	V
Data Rate Per Line	DR	1		53.125	Gbp/s
Bit Rate	BR			425	GBd

2、 Product Optical and Electrical Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit
Supply Voltage	V _{cc} V _{cc3.3-Tx} V _{cc3.3-Rx}	3.135	3.3	3.465	V

Power Consumption	Pc			8.5	W
Transceiver MgmtInitDuration Time				2000	ms
Transmitter					
Differential Peak-to-Peak Input Voltage Tolerance		900		10%	mV
Differential Termination Mismatch					V
Differential Input Return Loss(SDD11)			IEEE Equation (83E-5)		dB
Common-Mode to Differential Conversion and Differential to Common-Mode Conversion(SCD11,SDC11)			IEEE Equation (83E-6)		dB
Stressed Input Test		IEEE 120E.3.4.1			
Vcsel Wavelength		840	850	860	nm
Vcsel Beam Divergence				25°	
Receiver					
Differential Peak-to-Peak Output Voltage				900	mV
DC Common Mode Voltage	Vcm	-350		2850	mV
Common Mode Noise, RMS	VcmAC			17.5	mV
Differential Termination Mismatch				10	%
Differential Output Return Loss(SDD22)			IEEE Equation (83E-2)		dB
Common-Mode to Differential Conversion and Differential to Common-Mode Conversion(SCD22,SDC22)			IEEE Equation (83E-3)		dB
Near-End ESMW (Eye Symmetry Mask Width)			0.265		UI
Near-End Eye Height, Differential			70		mV
Far-End ESMW (Eye Symmetry Mask Width)			0.2		UI
Far-End Eye Height, Differential			30		mV
PD Wavelength		840	850	860	nm
IIC communication					
IIC Clock Frequency	-	/	400	1000	KHZ
Clock Stretching	-	/	/	500	us

Recommended Host Board Power Supply Circuit

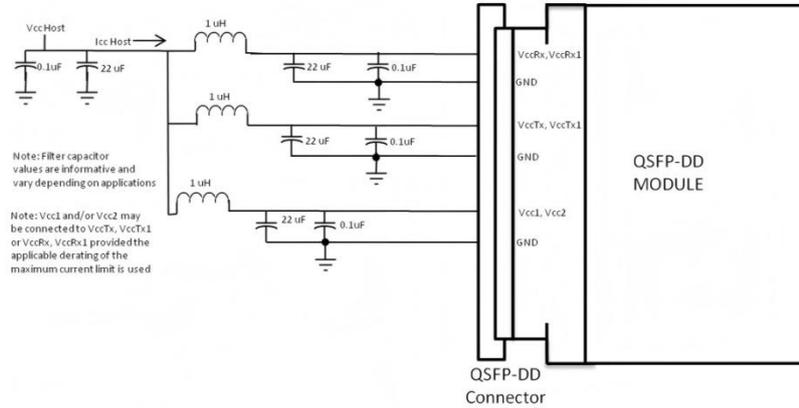


Figure 1: Recommended Host Board Power Supply Circuit

Recommended Interface Circuit

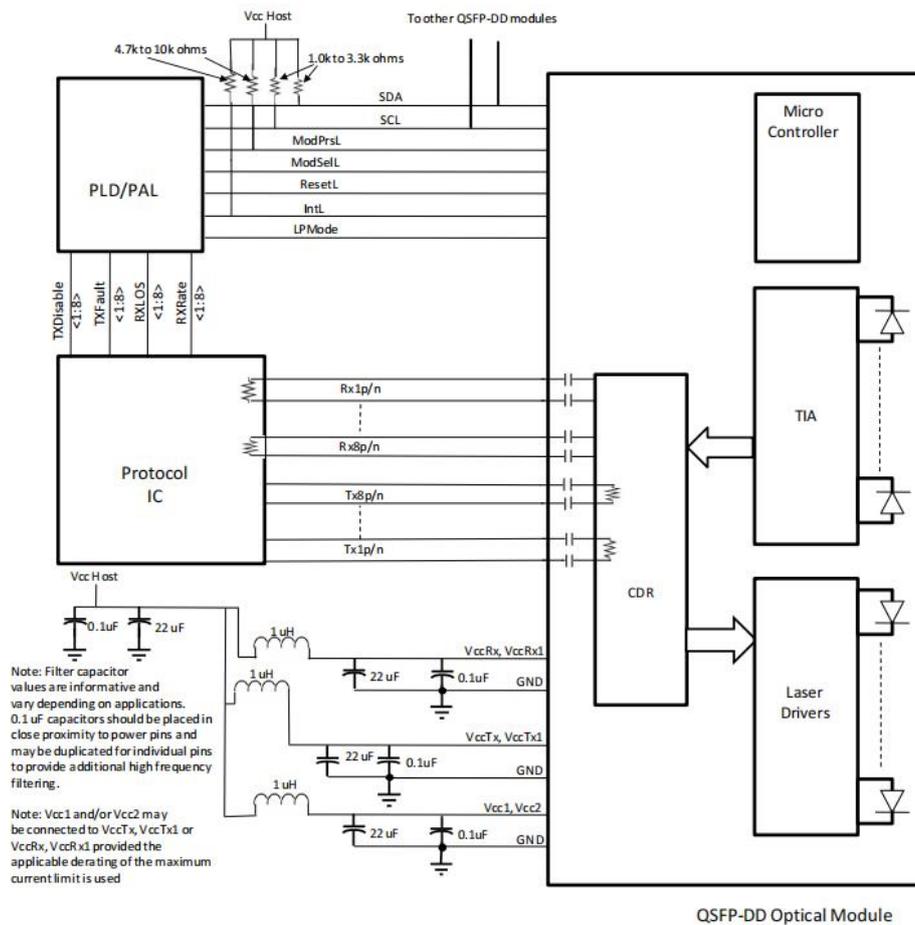


Figure 2: Recommended Interface Circuit

Pin-out Definition

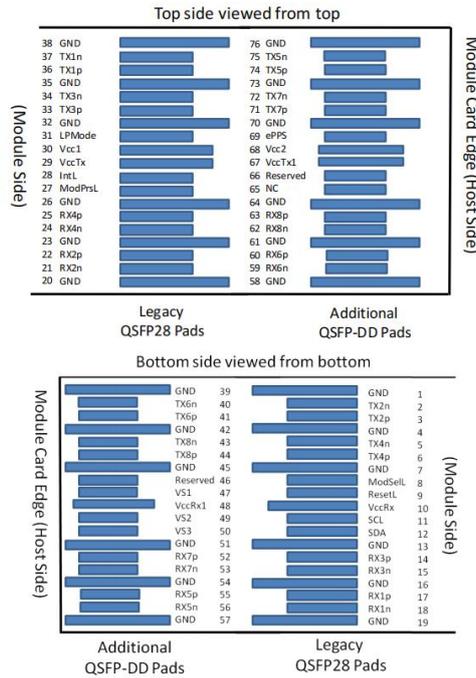


Figure3:Pin view

Pin Function Definitions

Pin	Logic	Symbol	Description	Note
1		GND	Ground	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	
4		GND	Ground	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	
7		GND	Ground	1
8	LVTTL-I	ModSelL	Module Select	
9	LVTTL-I	ResetL	Module Reset	
10		Vcc Rx	+3.3V Power Supply Receiver	2
11	LVC MOS-I/O	SCL	2-wire serial interface clock	
12	LVC MOS-I/O	SDA	2-wire serial interface data	
13		GND	Ground	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	
15	CML-O	Rx3n	Receiver Inverted Data Output	
16		GND	Ground	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	
18	CML-O	Rx1n	Receiver Inverted Data Output	

19		GND	Ground	1
20		GND	Ground	1
21	CML-O	Rx2n	Receiver Inverted Data Output	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	
23		GND	Ground	1
24	CML-O	Rx4n	Receiver Inverted Data Output	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	
26		GND	Ground	1
27	LVTTTL-O	ModPrsL	Module Present	
28	LVTTTL-O	IntL/RxLOSL	Interrupt. Optionally configurable as RxLOSL via the management interface (SFF-8636)	
29		VccTx	+3.3V Power supply transmitter	2
30		Vcc1	+3.3V Power supply	2
31	LVTTTL-I	InitMode	Initialization mode; In legacy QSFP applications, the InitMode pad is called LPMODE	
32		GND	Ground	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	
34	CML-I	Tx3n	Transmitter Inverted Data Input	
35		GND	Ground	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	
37	CML-I	Tx1n	Transmitter Inverted Data Input	
38		GND	Ground	1
39		GND	Ground	1
40	CML-I	Tx6n	Transmitter Inverted Data Input	
41	CML-I	Tx6p	Transmitter Non-Inverted Data Input	
42		GND	Ground	1
43	CML-I	Tx8n	Transmitter Inverted Data Input	
44	CML-I	Tx8p	Transmitter Non-Inverted Data Input	
45		GND	Ground	1
46		Reserved	For future use	3
47		VS1	Module Vendor Specific 1	3
48		VccRx1	3.3V Power Supply	2
49		VS2	Module Vendor Specific 2	3
50		VS3	Module Vendor Specific 3	3
51		GND	Ground	1
52	CML-O	Rx7p	Receiver Non-Inverted Data Output	
53	CML-O	Rx7n	Receiver Inverted Data Output	
54		GND	Ground	1
55	CML-O	Rx5p	Receiver Non-Inverted Data Output	
56	CML-O	Rx5n	Receiver Inverted Data Output	
57		GND	Ground	1
58		GND	Ground	1
59	CML-O	Rx6n	Receiver Inverted Data Output	

60	CML-O	Rx6p	Receiver Non-Inverted Data Output	
61		GND	Ground	1
62	CML-O	Rx8n	Receiver Inverted Data Output	
63	CML-O	Rx8p	Receiver Non-Inverted Data Output	
64		GND	Ground	1
65		NC	No Connect	3
66		Reserved	For future Use	3
67		VccTx1	3.3V Power Supply	2
68		Vcc2	3.3V Power Supply	2
69		Reserved	For future Use	3
70		GND	Ground	1
71	CML-I	Tx7p	Transmitter Non-Inverted Data Input	
72	CML-I	Tx7n	Transmitter Inverted Data Input	
73		GND	Ground	1
74	CML-I	Tx5p	Transmitter Non-Inverted Data Input	
75	CML-I	Tx5n	Transmitter Inverted Data Input	
76		GND	Ground	1

Note1: QSFP-DD uses common ground (GND) for all signals and supply (power). All are common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal common ground plane.

Note2: VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 shall be applied concurrently. Requirements defined for the host side of the Host Card Edge Connector are listed in Table 6. VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 may be internally connected within the module in any combination. The connector Vcc pins are each rated for a maximum current of 1000 mA.

Note3: All Vendor Specific, Reserved and No Connect pins may be terminated with 50 ohms to ground on the host. Pad 65 (No Connect) shall be left unconnected within the module. Vendor specific and Reserved pads shall have an impedance to GND that is greater than 10 Kohms and less than 100 pF.

Monitoring Specification

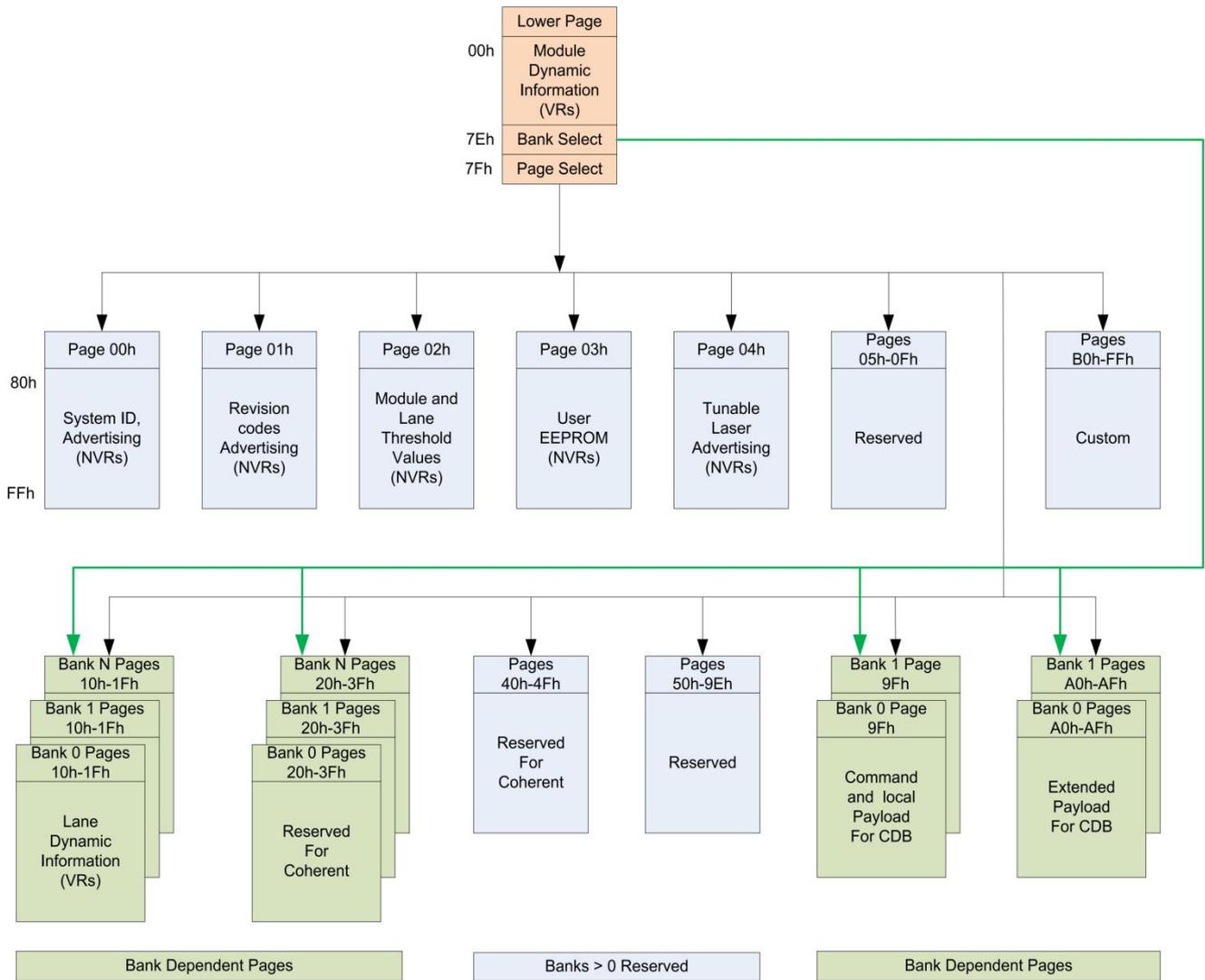


Figure4:Memory map

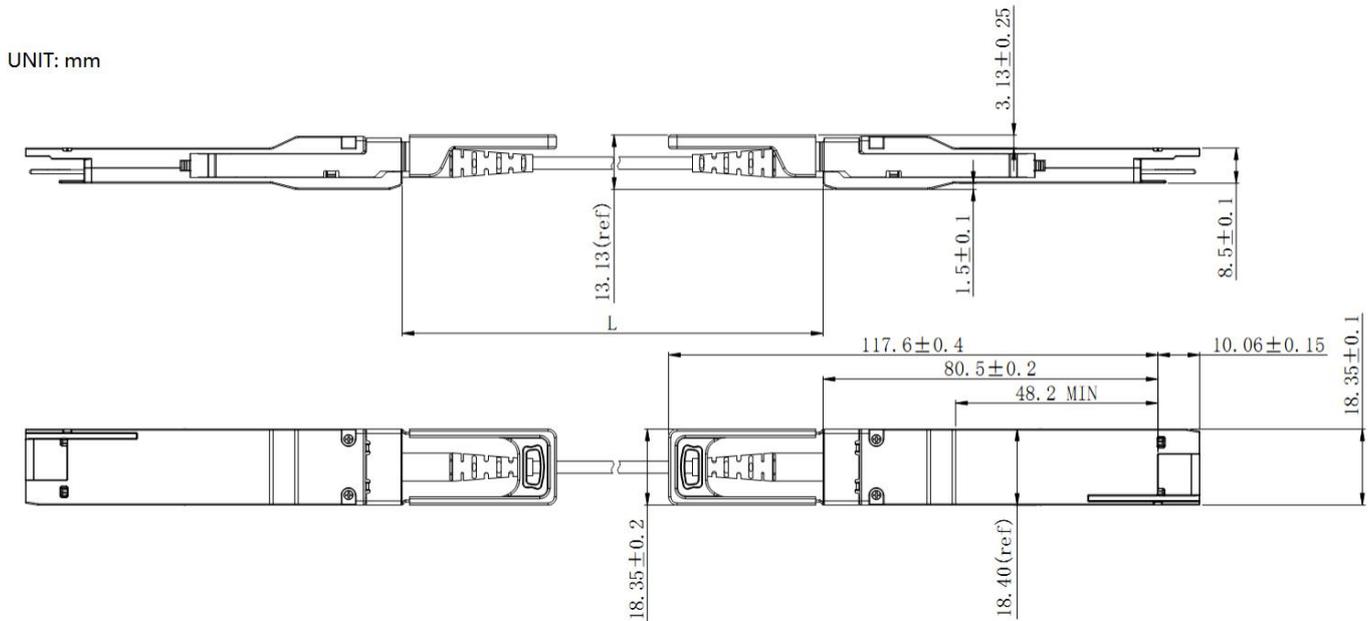
Memory map Table

Byte	Unit	Name	Description
Lower Page 00h			
0	1	Identifier	Identifier - Type of Serial Module - See SFF-8024.
1	1	Revision Compliance	Identifier – CMIS revision; the upper nibble is the whole number part and the lower nibble is the decimal part. Example: 01h indicates version 0.1, 21h indicates version 2.1.
2-3	2	ID and Status Area	Flat mem indication, CLEI present indicator, Maximum TWI speed, Current state of Module, Current state of the Interrupt signal.

4-7	4	Lane Flag Summary	Flag summary of all lane flags on pages 10h-1Fh.
8-13	6	Module-Level Flags	All flags that are not lane or data path specific.
14-25	12	Module-Level Monitors	Monitors that are not lane or data path specific.
26-30	5	Module Global Controls	Controls applicable to the module as a whole
31-36	6	Module-Level Flag Masks	Masking bits for the Module-Level flags
37-38	2	CDB Status Area	Status of most recent CDB command
39-40	2	Module Firmware Version	Module Firmware Version.
41-63	23	Reserved Area	Reserved for future standardization
64-82	19	Custom Area	Vendor or module type specific use
83-84	2	Inactive Firmware Version	Version Number of Inactive Firmware. Values of 00h indicates module supports only a single image.
85-117	33	Application Advertising	Combinations of host and media interfaces that are supported by module data path(s)
118-125	8	Password Entry and Change	Password Entry and Change
126	1	Bank Select Byte	Bank address of currently visible Page
127	1	Page Select Byte	Page address of currently visible Page
Upper Page 00h			
128	1	Identifier	Identifier - Type of Serial Module - See SFF-8024.
129-144	16	Vendor name	Vendor name (ASCII)
145-147	2	Vendor OUI	Vendor IEEE company ID
148-163	16	Vendor PN	Part number provided by vendor (ASCII)
164-165	8	Vendor rev	Revision level for part number provided by vendor (ASCII)
166-181	10	Vendor SN	Vendor Serial Number (ASCII)
182-183	2	Date code year	ASCII code, two low order digits of year (00=2000)
184-185	2	Date code month	ASCII code digits of month (01=Jan through 12=Dec)
186-187	2	Date code day of month	ASCII code day of month (01-31)
188-189	2	Lot code	ASCII code, custom lot code, may be blank
190-199	10	CLEI code	Common Language Equipment Identification code
200-201	2	Module power characteristics	Module power characteristics
202	1	Cable assembly length	Cable assembly length
203	1	Media Connector Type	Media Connector Type
204	1	5 GHz attenuation	Passive copper cable attenuation at 5 GHz in 1 dB increments
205	1	7 GHz attenuation	Passive copper cable attenuation at 7 GHz in 1 dB increments
206	1	12.9 GHz attenuation	Passive copper cable attenuation at 12.9 GHz in 1 dB increments
207	1	25.8 GHz attenuation	Passive copper cable attenuation at 25.8 GHz in 1 dB increments
208-209	2	Reserved	Reserved
210-211	2	Cable Assembly Lane Information	Cable Assembly Lane Information
212	1	Media Interface Technology	Media Interface Technology

213-220	8	Reserved	Reserved
221	1	Custom	Custom
222	1	Checksum	Includes bytes 128-221
223-255	33	Custom Info NV	Custom Info NV

Mechanical Dimension



Note:

- Diameter: 3mm
- Minimum bend radius:30mm
- Cable color:Orange(OM2),Aqua(OM3),Magenta(OM4)
- When $L \leq 1m$, the tolerance is +5cm
- When $1m \leq L \leq 4.5m$, the tolerance is +15cm
- When $5m \leq L \leq 14.5m$, the tolerance is +30cm
- When $L \geq 15m$, the tolerance is +2% m

Waring:

- The transceiver optics is supplied with a dust cover. This plug protects the transceiver optics during standard manufacturing processes by preventing contamination from air borne particles.It is recommended that the dust cover remain in the transceiver whenever an optical fiber connector is not inserted.
- Handling Precautions: This device is susceptible to damage as a result of electrostatic discharge (ESD). A static free environment is highly recommended. Follow guidelines according to proper ESD procedures.
- Laser Safety: Radiation emitted by laser devices can be dangerous to human eyes. Avoid eye exposure to direct or indirect radiation.